

Title (en)

METHOD FOR METALLIZING AN ELECTRIC COMPONENT AND ELECTRIC COMPONENT

Title (de)

VERFAHREN ZUR KONTAKTIERUNG EINES ELEKTRISCHEN BAUELEMENTS UND ELEKTRISCHES BAUELEMENT

Title (fr)

PROCEDE POUR LA METALLISATION D'UN COMPOSANT ELECTRIQUE, ET COMPOSANT ELECTRIQUE AINSI OBTENU

Publication

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Application

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Abstract (en)

[origin: DE19816245A1] In the semiconductor substrate are formed contact bores filled with electrically conductive material, with the bores insulated from the substrate, but are conductively coupled to the component. On the rear side of the substrate are formed contacts in electric contact with the contact bores. The formation of contact bores comprises lithographic defining and plasma etching of the contact bores. Typically the contact bores are filled with tungsten or copper. In the contact bores is deposited an insulating SiO₂ film and an adhesive layer for the conductive material.

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